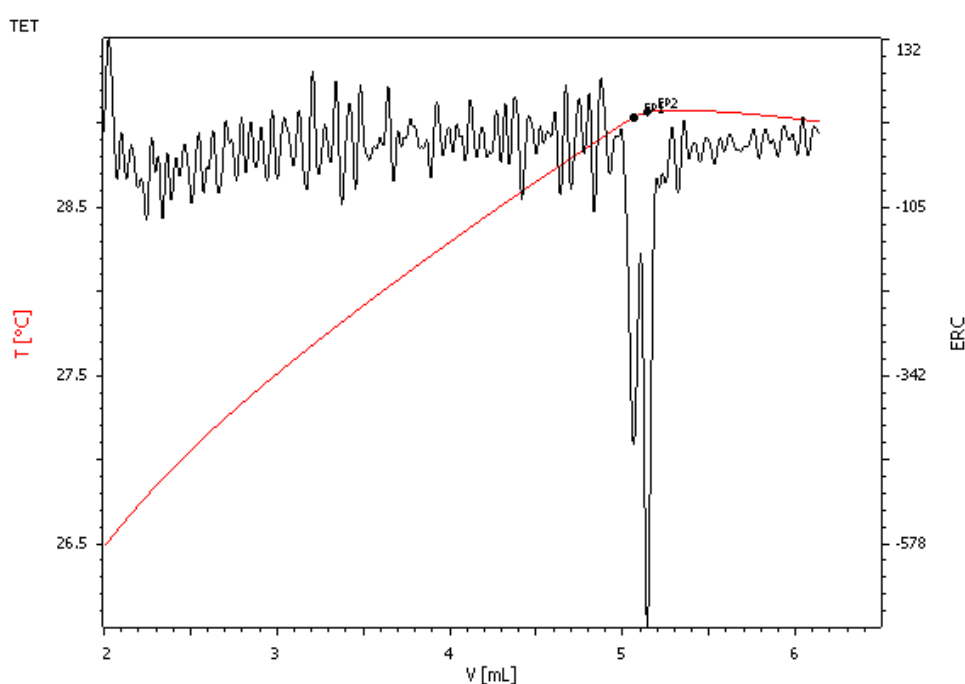


# Determination of potassium hydroxide and silica in alkaline etch solution



This Application Note describes a direct thermometric endpoint titration (TET) for the determination of concentrated potassium hydroxide solutions which had been used for the etching of substrates containing silicon.

# Method description

## Sample

High concentrated potassium hydroxide solution which contains a small amounts of SiO<sub>2</sub> generated during the etch process of silicon.

## Sample preparation

No sample preparation is necessary.

## Configuration

859 Titrotherm	2.859.1010
HF Thermoprobe	6.9011.040
804 Ti Stand	2.804.0040
802 Propeller stirrer	2.802.0040
Dosing unit 10 mL	6.3032.210
800 Dosino	2.800.0010
PFA titration vessel	6.1450.210
Mounting ring	6.2036.000
Titration vessel lid	6.1414.010

## Solutions

Titrant	c(HCl) = 2 mol/L
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## Analysis of samples

Approx. 2–2.5 g sample is weighed accurately into a clean dry PFA titration vessel and 30 mL deionized water is added. The solution is titrated with c(HCl)=2 mol/L to a second exothermic endpoint.

## Determination of the method blank

For both KOH and SiO<sub>2</sub> a linear regression of different sample sizes against titrant consumption is performed. Therefore approx. 1–3 g sample is weighed accurately into a PFA titration vessel, diluted with 30 mL deionized water and titrated to a second exothermic endpoint. For the linear regression of KOH the consumption to the first endpoint is used. For the linear regression of SiO<sub>2</sub> the consumption corresponds to the volume difference between the second and the first endpoint.

## Parameters

Titrant dose rate	1 mL/min
No. of exothermic endpoints	2
ERC EP1 (exothermic)	-350
ERC EP2 (exothermic)	-350
Damping until	0.2 mL
Evaluation start	2 mL
Filter factor	15
Stirring speed	8

## Result

%KOH (n = 5)	s <sub>rel</sub> (%)
30.00	0.79
%SiO <sub>2</sub> (n = 5)	s <sub>rel</sub> (%)
0.12	2.32